

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteri	stic	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	Single Diode	M	300	V
Repetitive Feak Reverse voltage	Series Connection	$V_{RRM}$	600	
Working Peak Reverse Voltage Single Diode V <sub>RV</sub>		$V_{RWM}$	300	V
DC Blocking Voltage	Series Connection	$V_R$	600	V
RMS Reverse Voltage		V <sub>R(RMS)</sub>	212	V
Forward Current (Note 6)	Single Diode Loaded	l <sub>F</sub>	250	mA
Forward Current (Note 6)	Double Diodes Loaded		140	
Non-Repetitive Peak Forward Surge Current Square Wave @ t = 1.0µs		I <sub>FSM</sub>	4.5	Α
Repetitive Peak Forward Current (Note 6)		I <sub>FRM</sub>	625	mA

## **Thermal Characteristics**

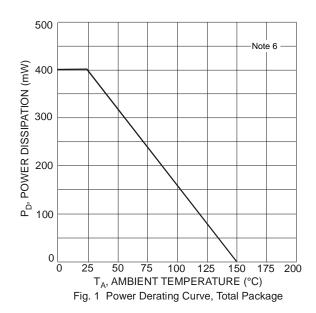
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_{D}$	400	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	312	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

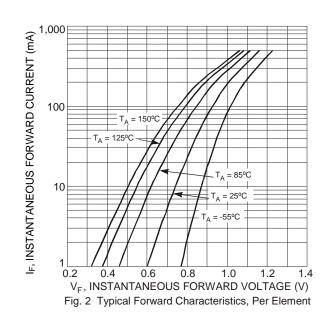
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	300	_	V	$I_R = 100 \mu A$
Forward Voltage	V <sub>F</sub>	_	1.1	V	I <sub>F</sub> = 100mA
Reverse Current (Note 7)	1-	_	150	nA	$V_R = 250V$
Neverse Current (Note 1)	IR	_	75	μΑ	$V_R = 250V, T_J = +150$ °C
Total Capacitance	C <sub>T</sub>	_	2.0	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	4	_	50	ns	$I_F = I_R = 30 \text{mA},$
Reverse Recovery Time	t <sub>RR</sub>				$I_{RR} = 0.1 \times I_{R}, R_{L} = 100\Omega$

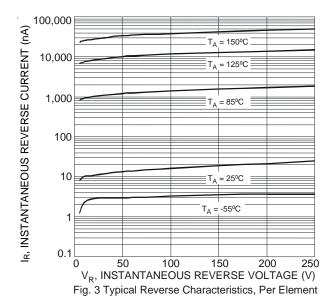
Notes:

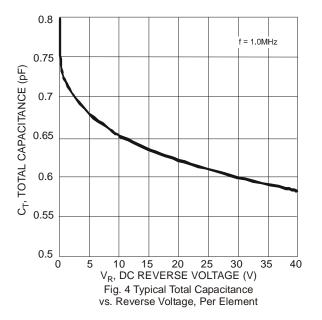
- 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.
- 7. Short duration pulse test used to minimize self-heating effect.







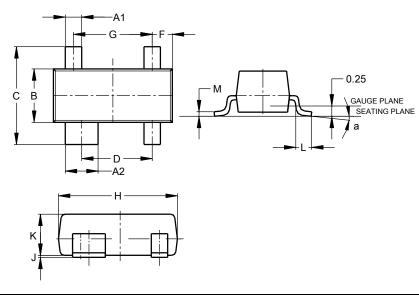




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

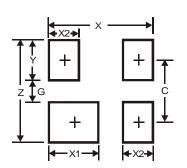
#### **SOT143**



SOT143				
Dim	Min	Max	Тур	
A1	0.37	0.51	0.400	
A2	0.77	0.93	0.800	
В	1.20	1.40	1.30	
С	2.28	2.48	2.38	
D	1.58	1.83	1.72	
F	0.45	0.60	0.49	
G	1.78	2.03	1.92	
Η	2.80	3.00	2.90	
J	0.013	0.10	0.05	
K	0.89	1.00	-	
L	0.46	0.60	0.50	
M	0.085	0.18	0.11	
а	0°	8°	_	
All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



### SOT143

Dimensions	Value (in mm)		
Z	2.70		
G	1.30		
Х	2.50		
X1	1.00		
X2	0.60		
Y	0.70		
С	2.00		



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